

COMPLETE LISTING OF THE CLAIMS

The following lists all of the claims as presented for further examination in the above-identified patent application.

Claims 1-17 (Canceled)

18. (Previously Presented) An optical device package comprising:
a device that emits an optical signal from a major surface of the device;
a sub-mount containing electrical traces that are electrically connected to the device;
a cap attached to the sub-mount so as to form a cavity enclosing the device;
an optical element residing within the cavity on an interior surface of the cap and in a path of the optical signal; and
an alignment post glued to an exterior surface of the cap and aligned with the path of the optical signal.

19. (Previously Presented) The package of claim 18, wherein the device comprises a VCSEL.

20. (Previously Presented) The package of claim 18, wherein the sub-mount comprises a semiconductor substrate.

21. (Previously Presented) The package of claim 18, wherein flip-chip bonding electrically connects bonding pads on a front face of the device to the electrical traces in the sub-mount, and the optical signal emerges from a back face of the device.

22. (Previously Presented) The package of claim 18, the cap comprises a semiconductor substrate.

23. (Previously Presented) The package of claim 18, wherein bonding of the cap to the sub-mount hermetically seals the cavity.

24. (Previously Presented) The package of claim 18, wherein the alignment post is glued to the cap where the optical signal emerges from the cap.

25. (Previously Presented) The package of claim 24, wherein the alignment post comprises a hollow cylinder having an inner diameter larger than a beam profile of the optical signal.

26. (Previously Presented) The package of claim 18, wherein the optical element comprises a lens.

THE PATENT LAW OFFICES
OF DAVID MILLERS
6560 ASHFIELD COURT
SAN JOSE, CA 95120
PH: (408) 927-6700
FX: (408) 927-6701